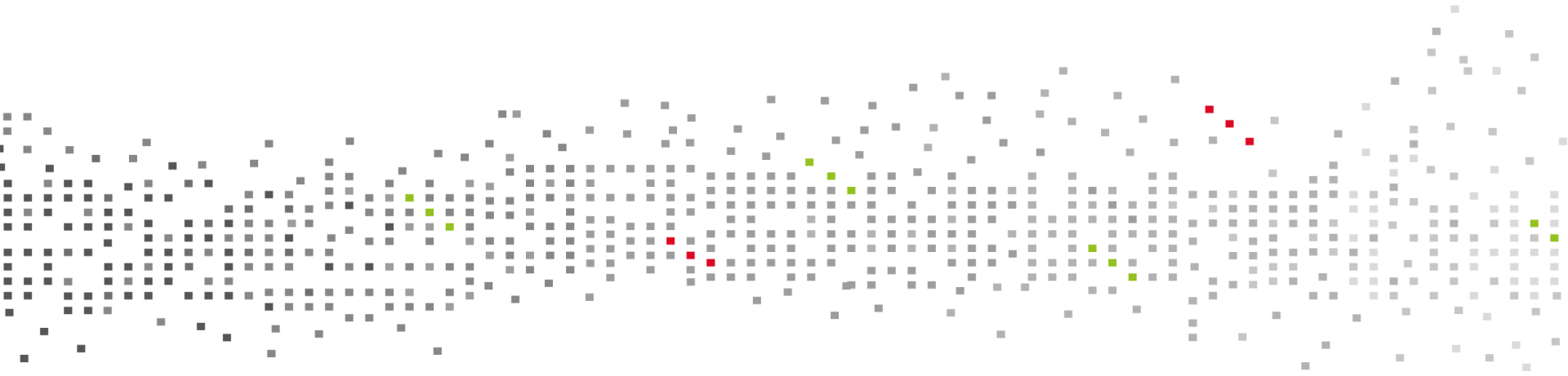


A decorative graphic consisting of a grid of small squares, some of which are colored in shades of green and red, arranged in a pattern that resembles a micro LED array. The pattern is set against a white background and is partially obscured by a green banner at the bottom.

MICRO LED ARRAY FOR SMART LIGHTING SYSTEM AND AUTOMOTIVE HEADLAMPS APPLICATIONS

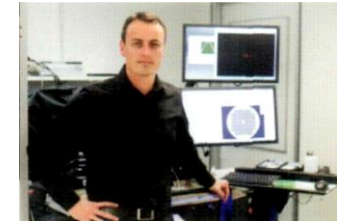


PHOTONICS AT DOPT

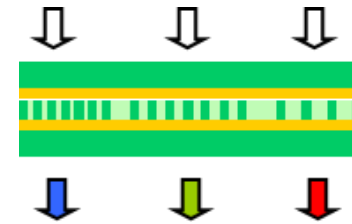
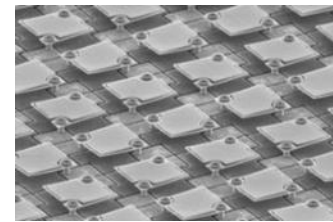
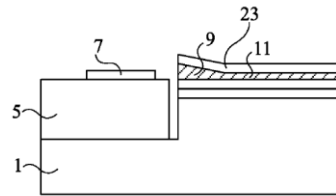
GaN LED ARRAY | Hani kanaan- BASEL | 12 /12/2016

A FEW FIGURES

Created in 1978
300 researchers,
engineers and PhD
students



400 patents in portfolio
60 new/year



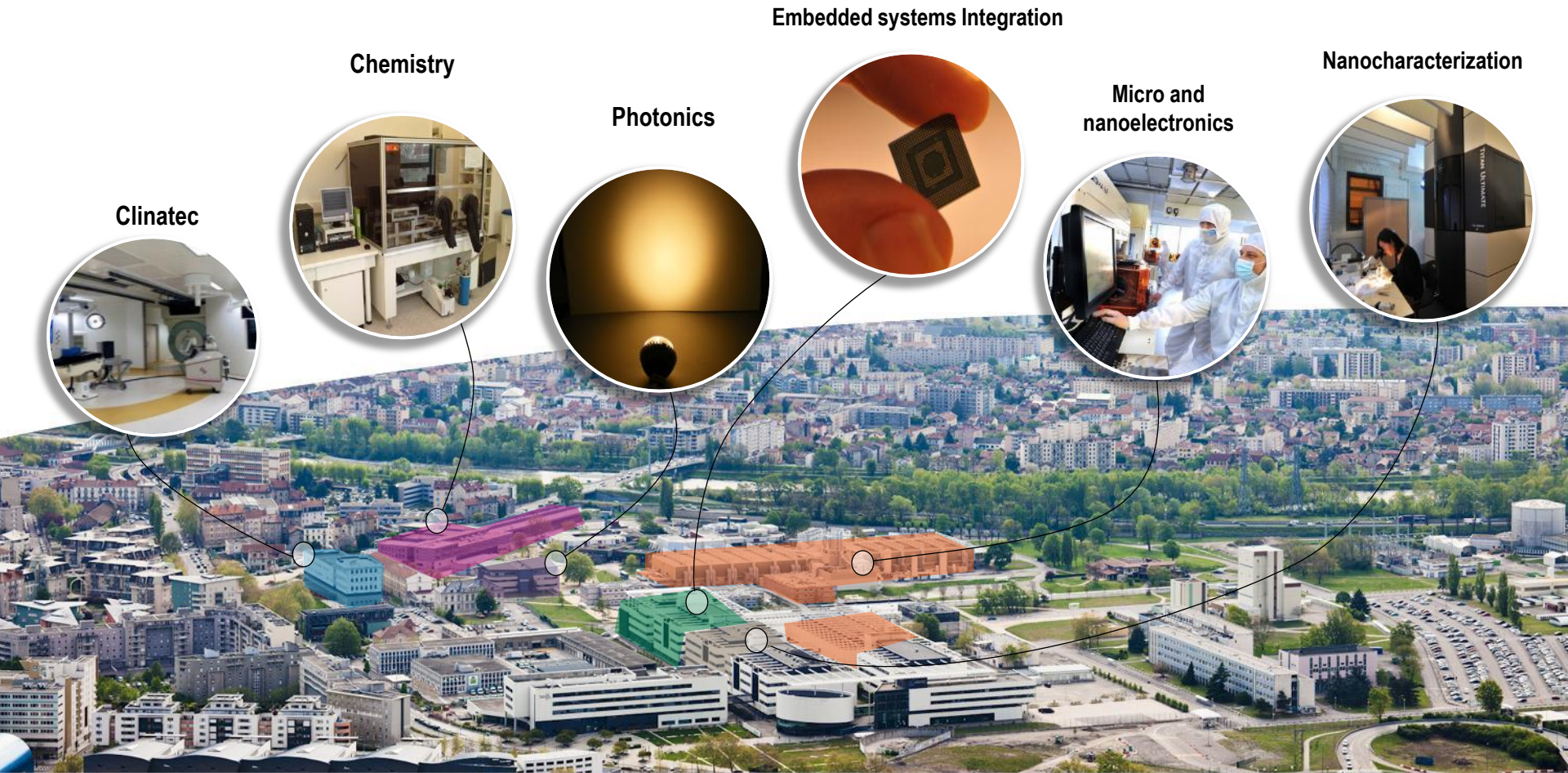
50-60 M€ budget
~10% for CAPEX

Dedicated clean rooms for III-V and II-VI materials on versatile substrate geometries up to 150 mm

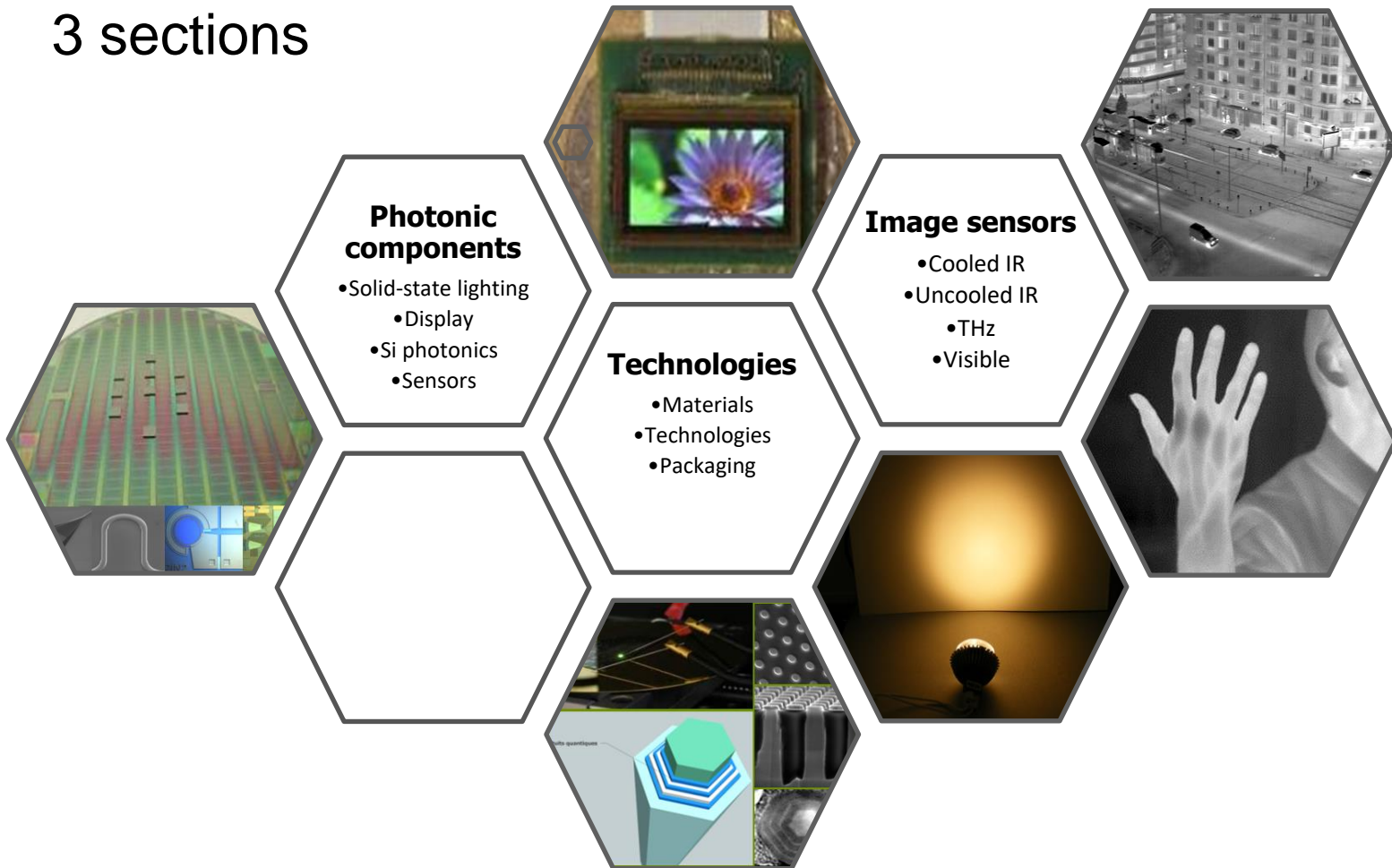
Access to Leti clean rooms in 200 and 300 mm through many photonic processes and technology modules

Electro-optical test and characterization facilities

RESEARCH PLATFORMS AT GRENOBLE



3 sections



Core competencies : component design and modeling, III-V and II-VI materials, fabrication technologies, characterization



SMART LIGHTING SYSTEM

What is ?

- lighting elements , detectors , electronics components , ...

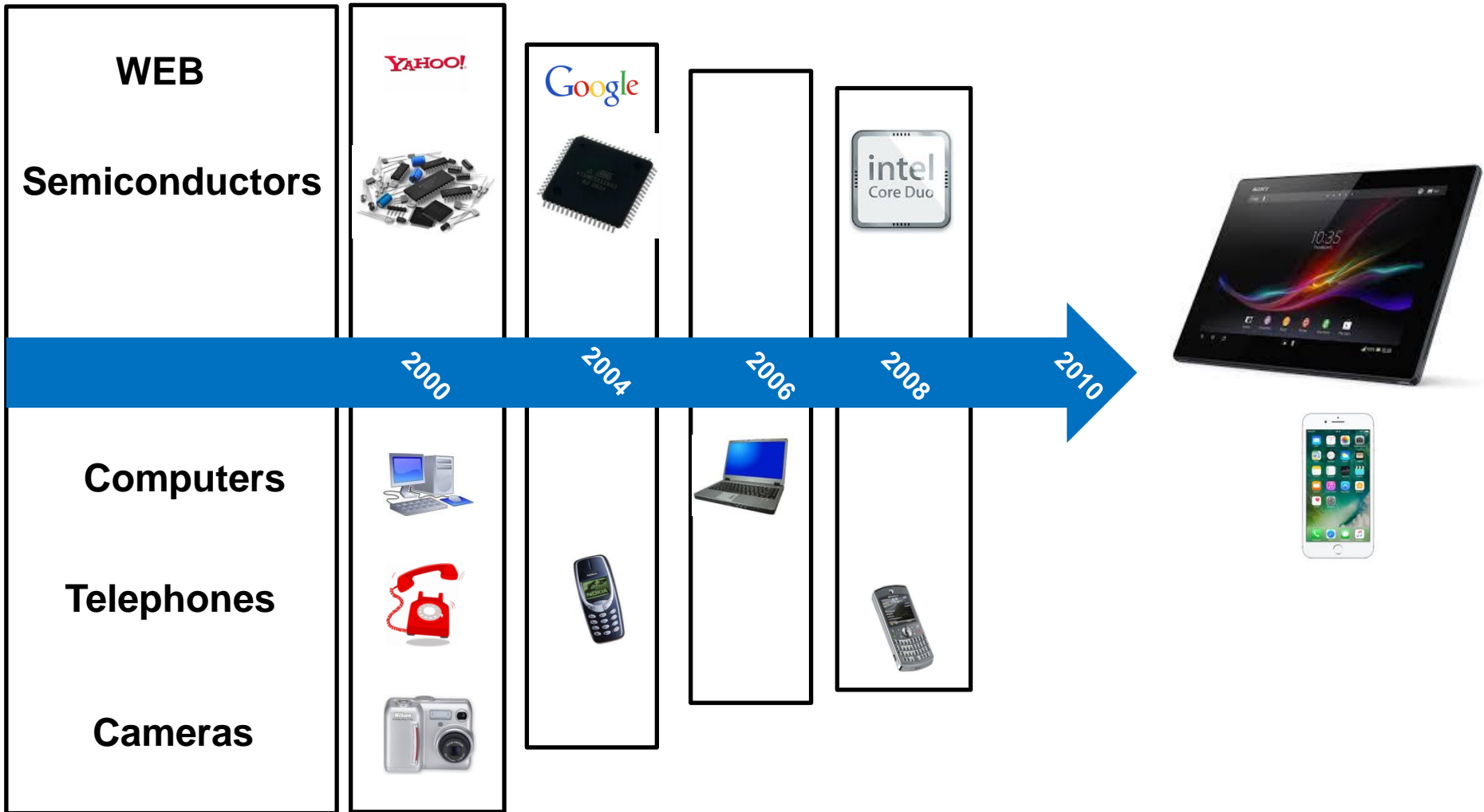
For what ?

- Automatic dimming, projection, daylight sensor, presence sensor, beam control, color control,
- cost reduction &/or functionality enhancement
- New business potential

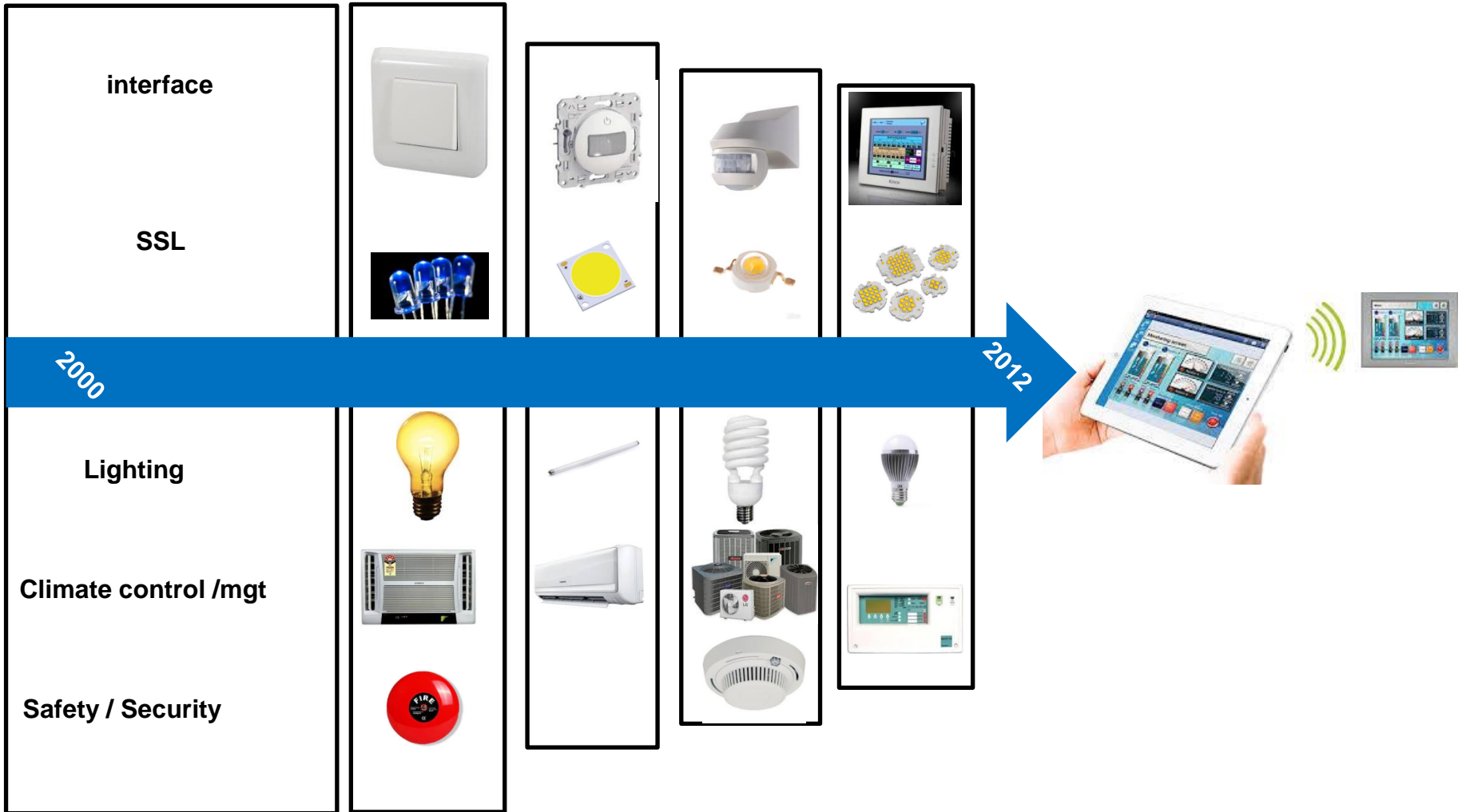
How to do it

- Sensor, imageur, light sources ,processor & Scenarri ...

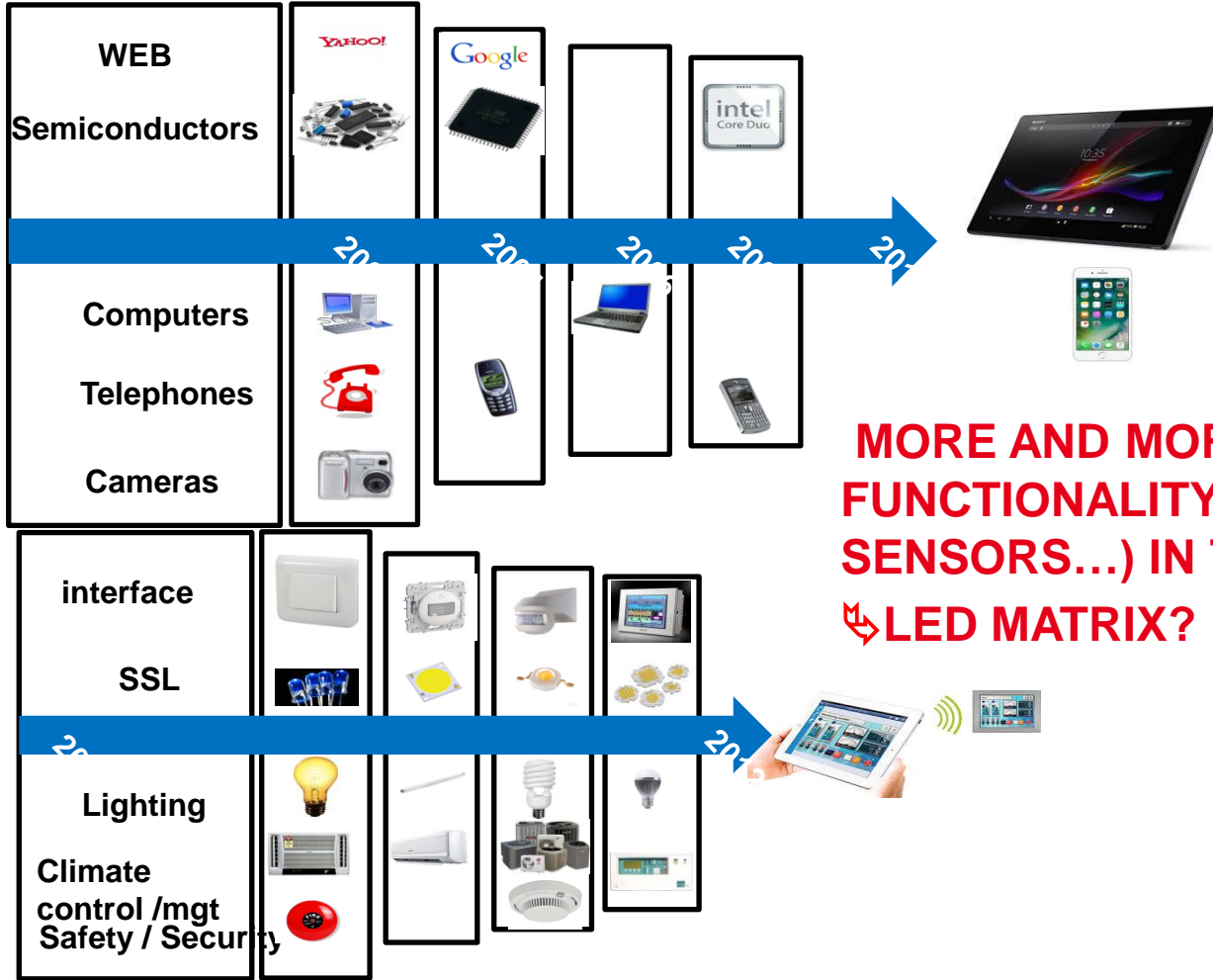
CONSUMER ELECTRONICS INDUSTRY CONVERGENCES



BUILDING INDUSTRY CONVERGENCE PROGRESS



WHAT NEXT ?



MORE AND MORE INTEGRATION OF FUNCTIONALITY (LIGHTING, DISPLAY SENSORS...) IN THE SAME COMPONENT
↳ LED MATRIX?

HIGH DENSITY LED ARRAY FOR ADAPTIVE STREET LIGHTING



Spacial & Dynamic control of light flux



WHY HIGHT DEFINITION LED GAN MICRODISPLAYS?

Head-mounted Displays
→ see-through systems



Augmented reality
See more, hands-free.



New applications /
New markets

- ↪ New requirements:
 - system
 - display

System requirement:

- Compactness
- Field of view (immersion)

Microdisplay requirement:

- Image quality
- Compactness
- Low consumption
- High brightness

Emissive
OLED microdisplay:

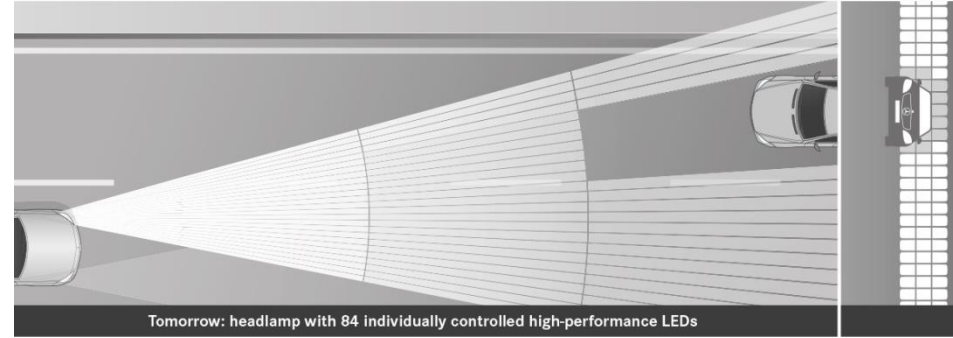
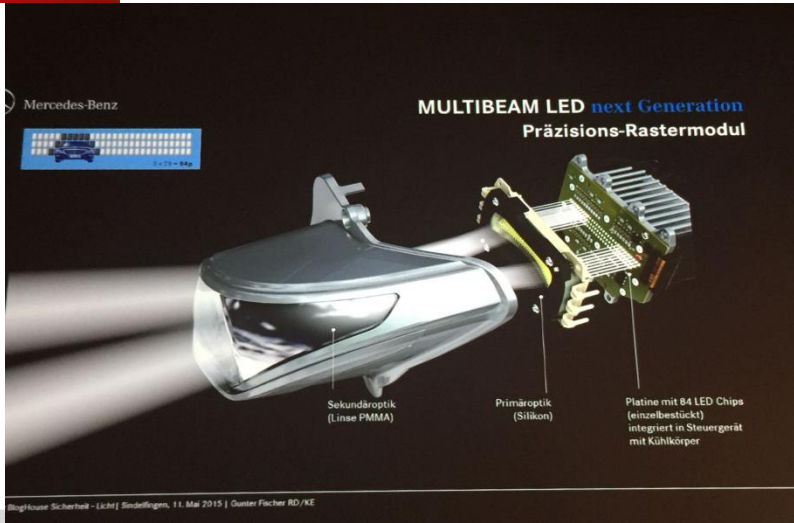


1000 Cd/m²

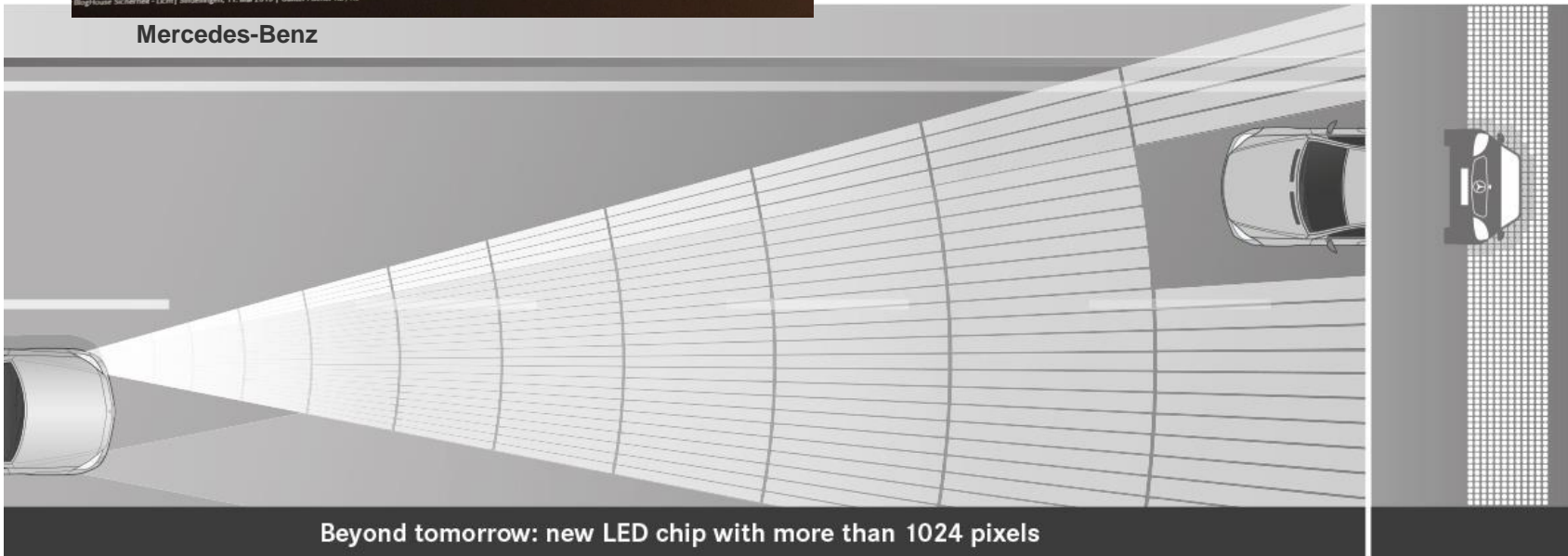
Need more..

New display:
↪ LED GaN microdisplay

WHY HIGH DEFINITION LED GAN ARRAY HEADLAMPS? STATE OF THE ART



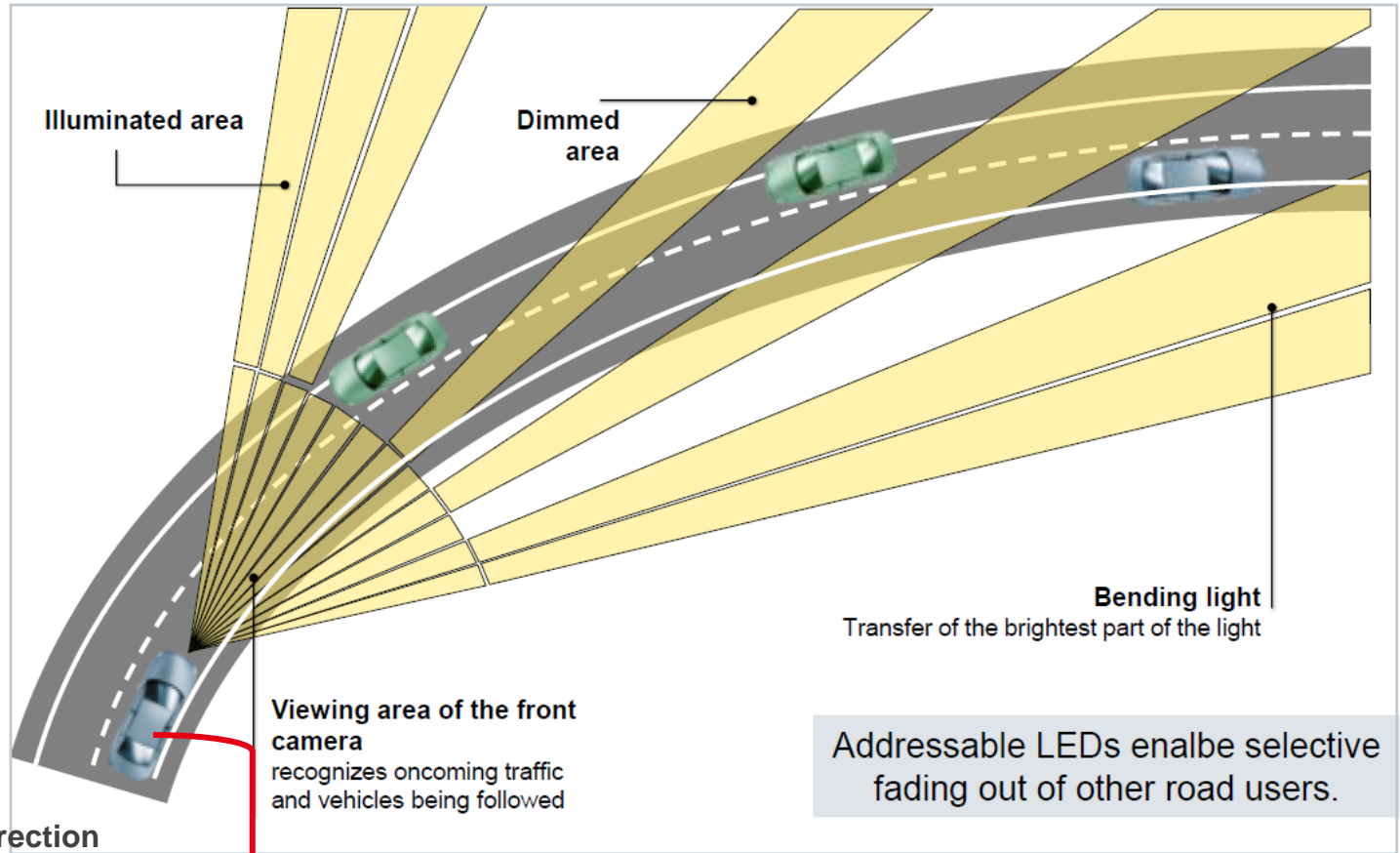
Mercedes-Benz



μAFS demonstrator (OSRAM)

Tomorrow's LED technology

WHY HIGHT DEFINITION LED GAN ARRAY HEADLAMPS?



System requirement:

- Compactness
- Field of view :
 - -30° to $+30^{\circ}$ in H direction
 - -10° to 4° in V direction
 - Color temperature 5000-6000K
 - Resolution of $0,1^{\circ}$ in Both direction
 - 60-70 μm Pixel size
 - Pixel dimming
 - ASIC for pixel driving

Viewing area of the front camera
recognizes oncoming traffic and vehicles being followed

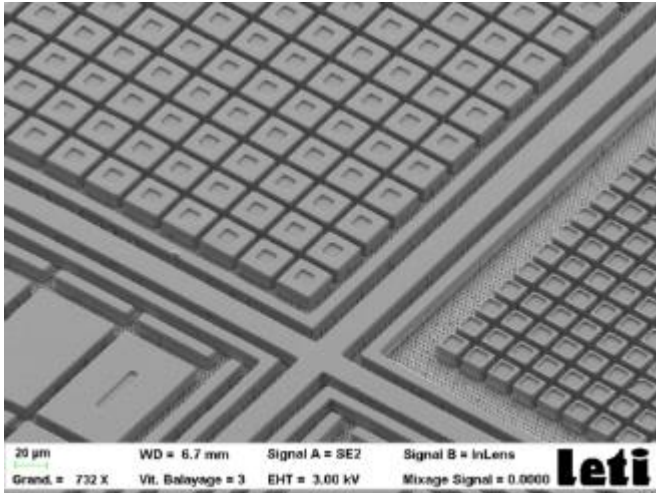
Addressable LEDs enable selective fading out of other road users.

Various Matrix LED Light Patterns (LEDinside/HELLA)

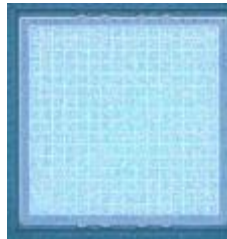
New high brightness LED GAN MATRIX

HOW TO MAKE A GAN LED ARRAY?

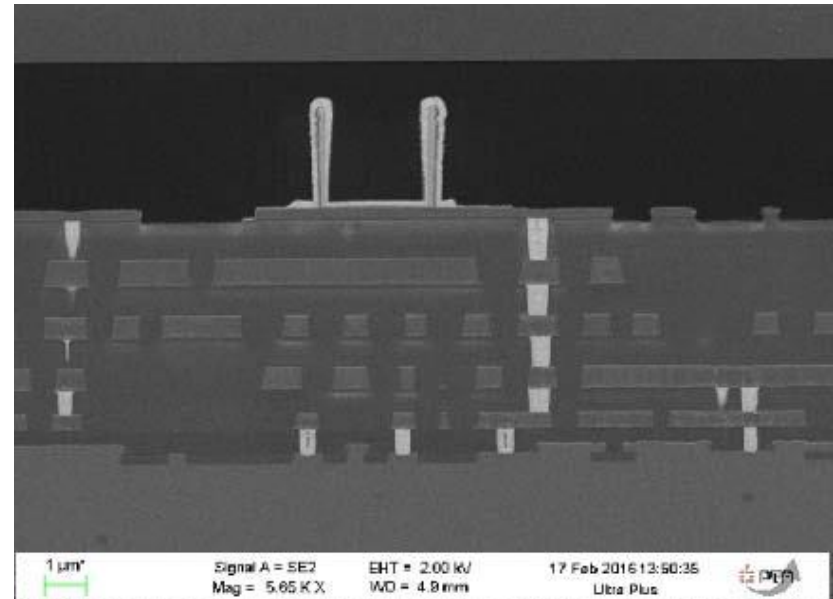
1-GaN on Sapphire Substrate etching For electrically independent pixels



Narrow GaN etching
High active area ratio
Compatible high pixel numbers



2-High voltage Silicon Interposer driver circuit AC-LED



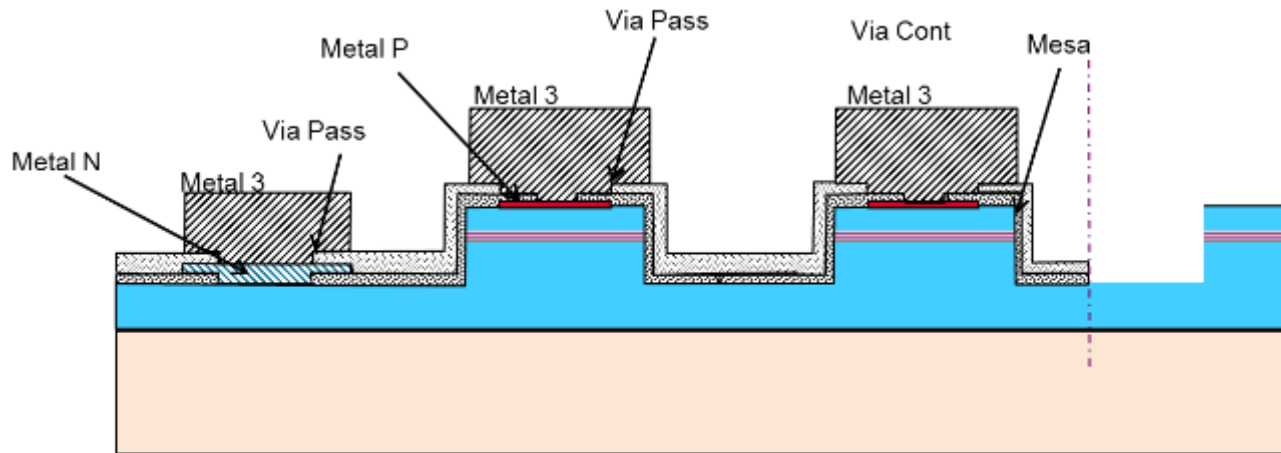
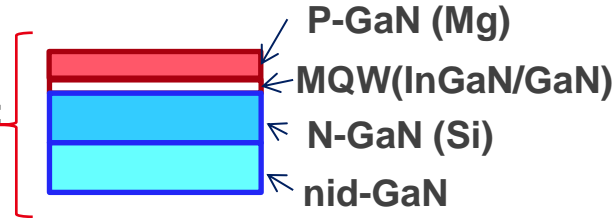
3-Hybridization for electrical connection

DEVELOPMENT OF 10 μM PITCH GAN LED ARRAY

GaN Diode process on sapphire

- Towards small-pitch LED arrays
- Development of dedicated process

Epi LED structure:
(MOCVD)



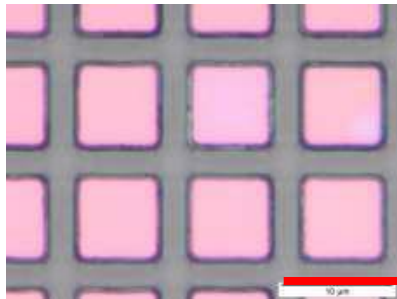
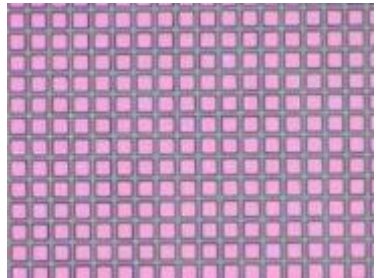
Mesa
 Metals P/N
 Insulations



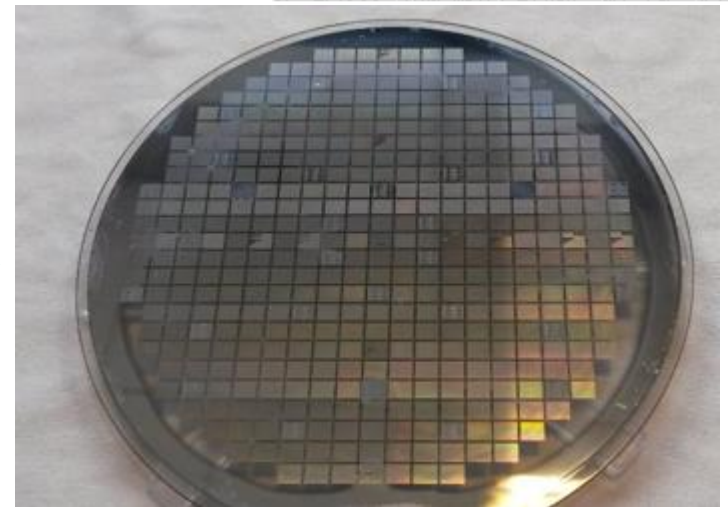
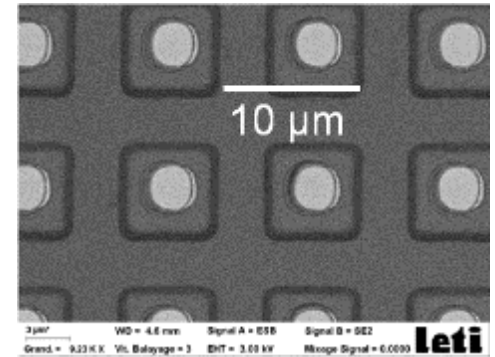
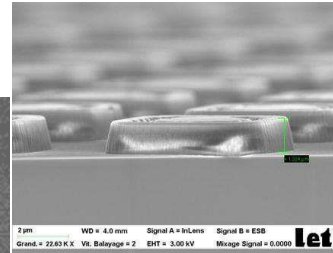
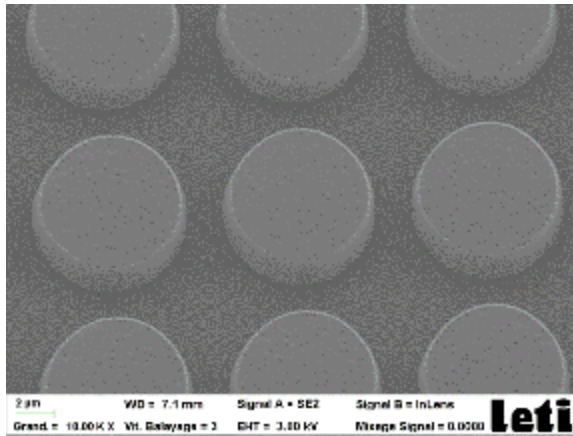
- Challenges:**
- Epitaxy quality
 - Contacts
 - ...Small-pitch

DEVELOPMENT OF 10 μM PITCH GAN LED ARRAY

GaN LED array were fabricated on 2-in. and 4-in. sapphire substrates.



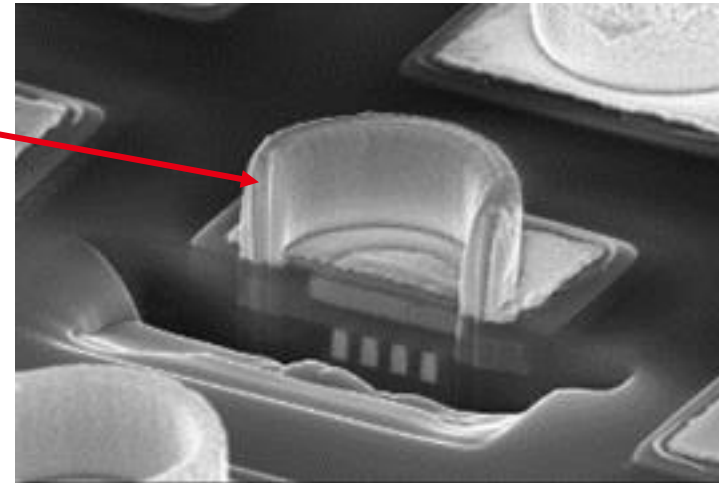
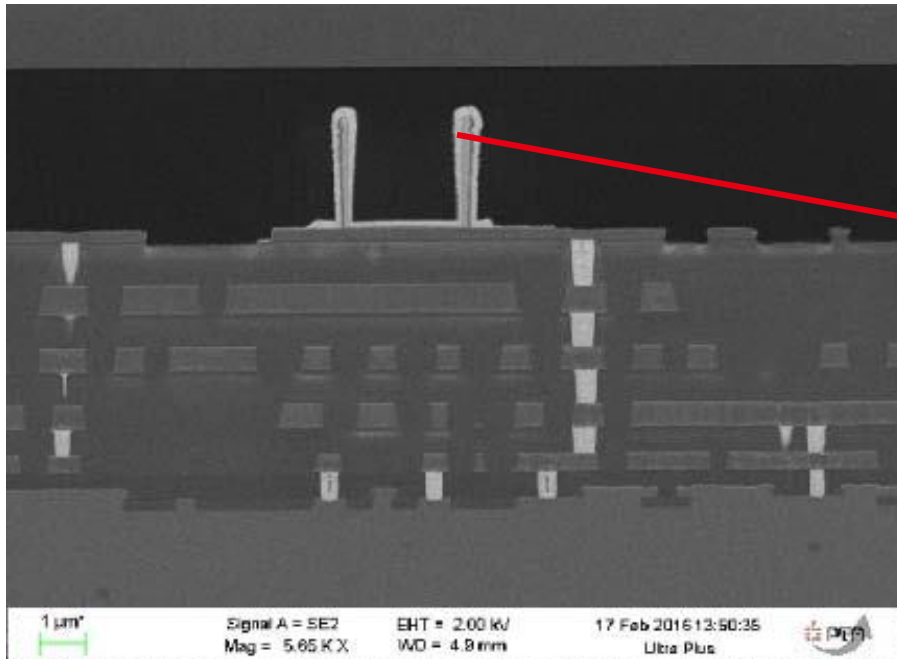
10 μm



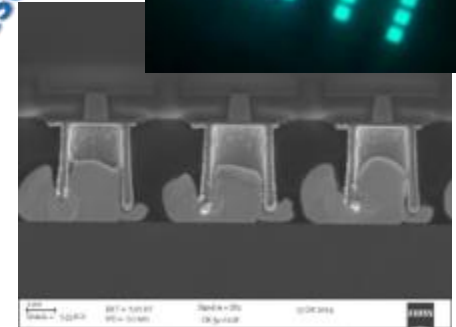
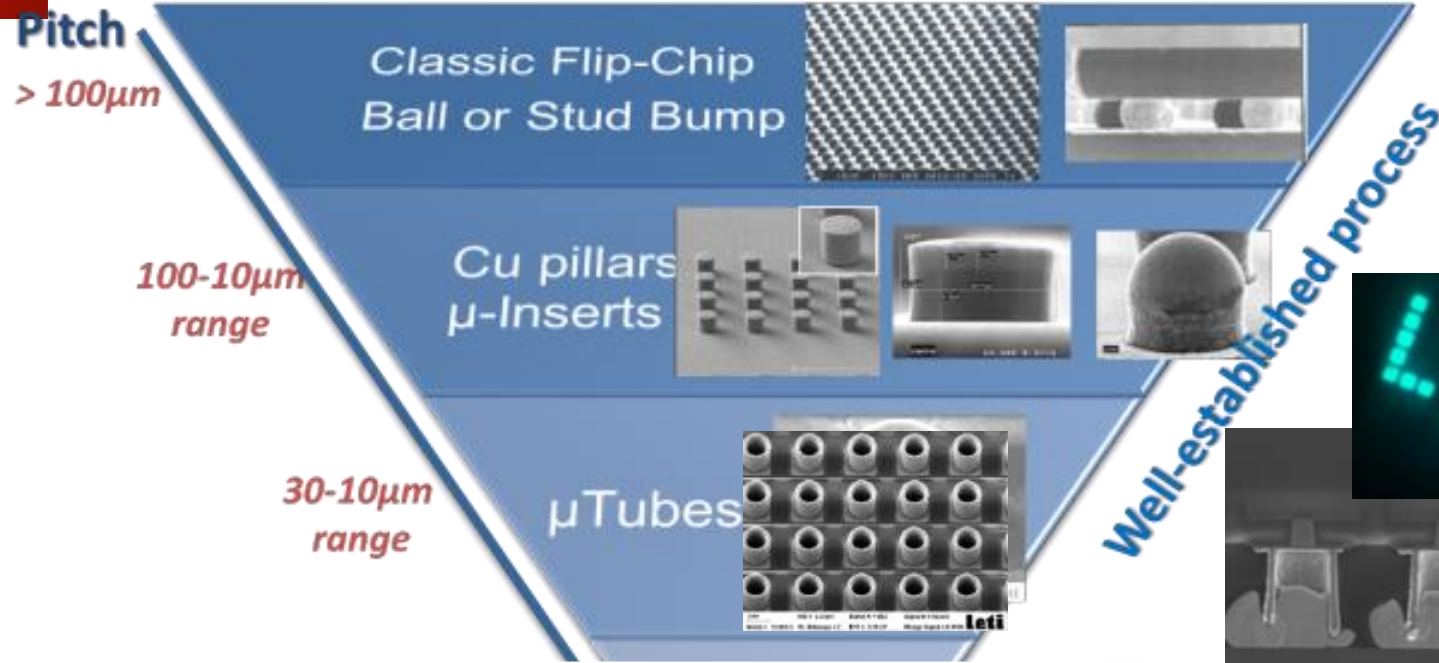
Each die: GaN array :
300 x 252 = 75 600 pixels
at 10 μm pitch

DEVELOPMENT OF 10 μm PITCH SILICON INTERPOSER DRIVER CIRCUIT

The CMOS circuit is built on a silicon substrate



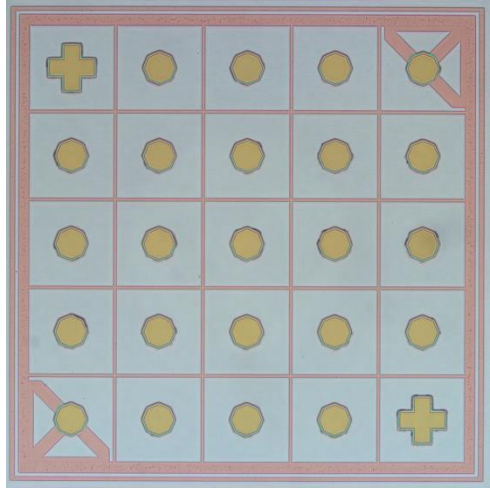
LED MATRIX HYBRIDIZATION ON CMOS TECHNOLOGIES



DEMONSTRATORS OF 178 μm PITCH BLUE GAN LED ARRAY FOR PROJECTION APPLICATION



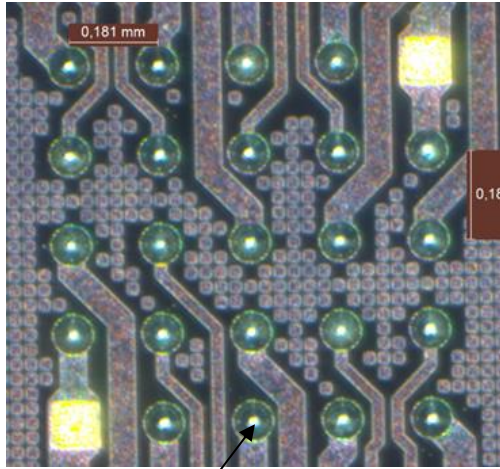
LED array on sapphire



200 μm

GaN side

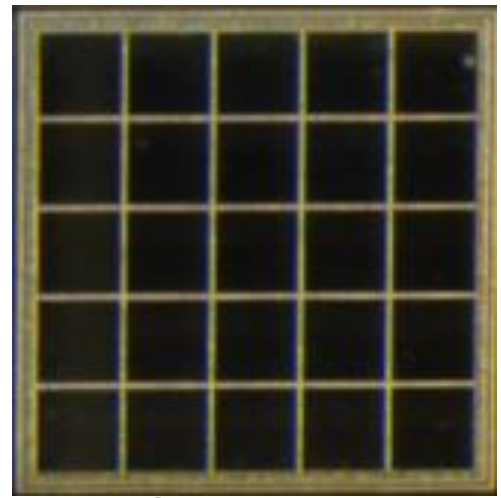
Passive array on Si



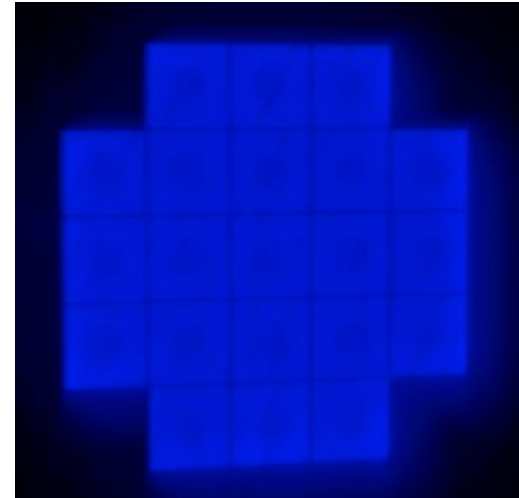
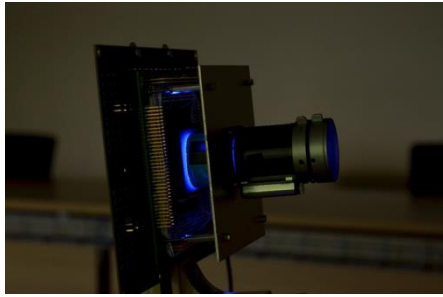
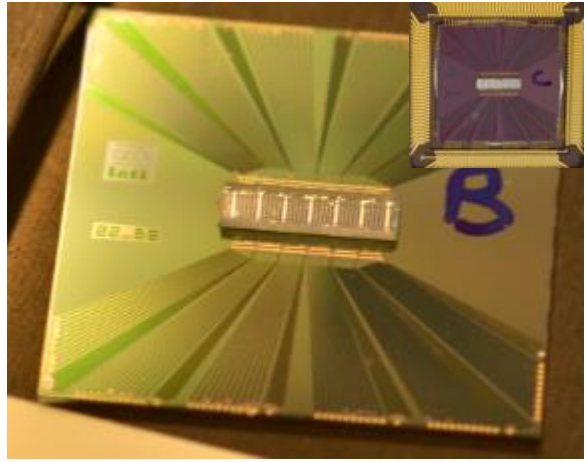
Solder ball

200 μm

Hybridized LED array



Sapphire side

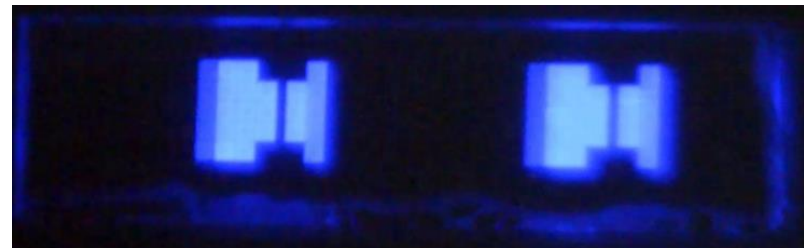


Sapphire side

CONFIDENTIEL

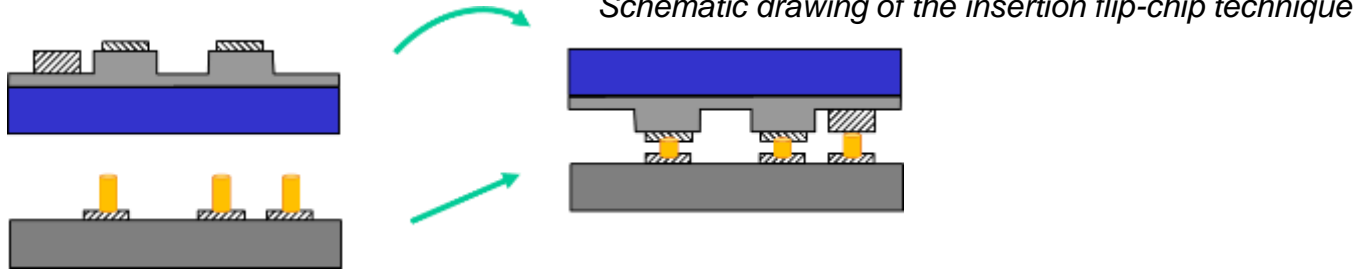
DEMONSTRATORS OF 178 μm PITCH BLUE GAN LED ARRAY FOR AUTOMOTIVE HEADLAMPS

Blue LED matrix
projection
CEA / LETI 2016



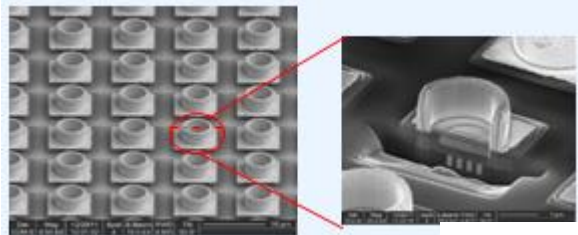
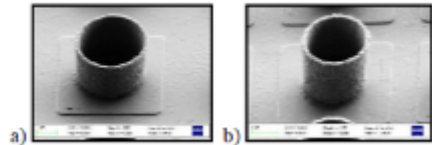
HYBRIDIZATION WITH MICRO-TUBE TECHNOLOGY

Principle: μ Tube inserted in pad



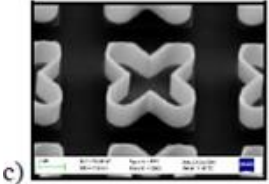
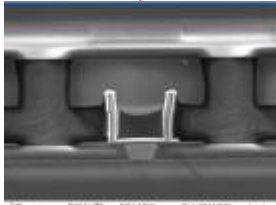
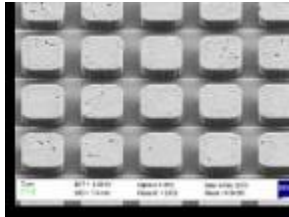
Microtubes on silicon side:

silicon side: ROC, active-matrix,...



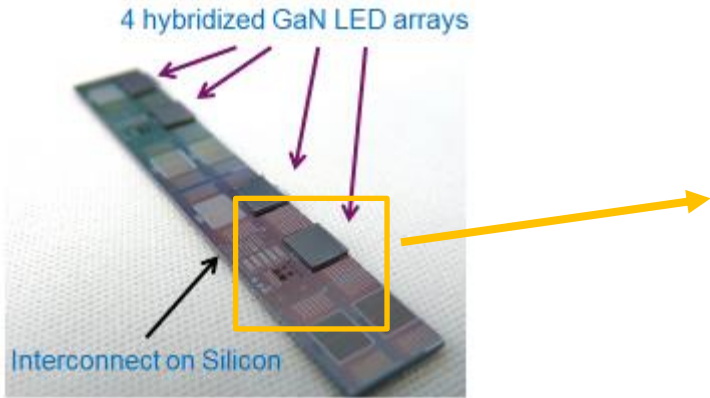
Pads on opposite side:

top side: sensor, ...GaN array



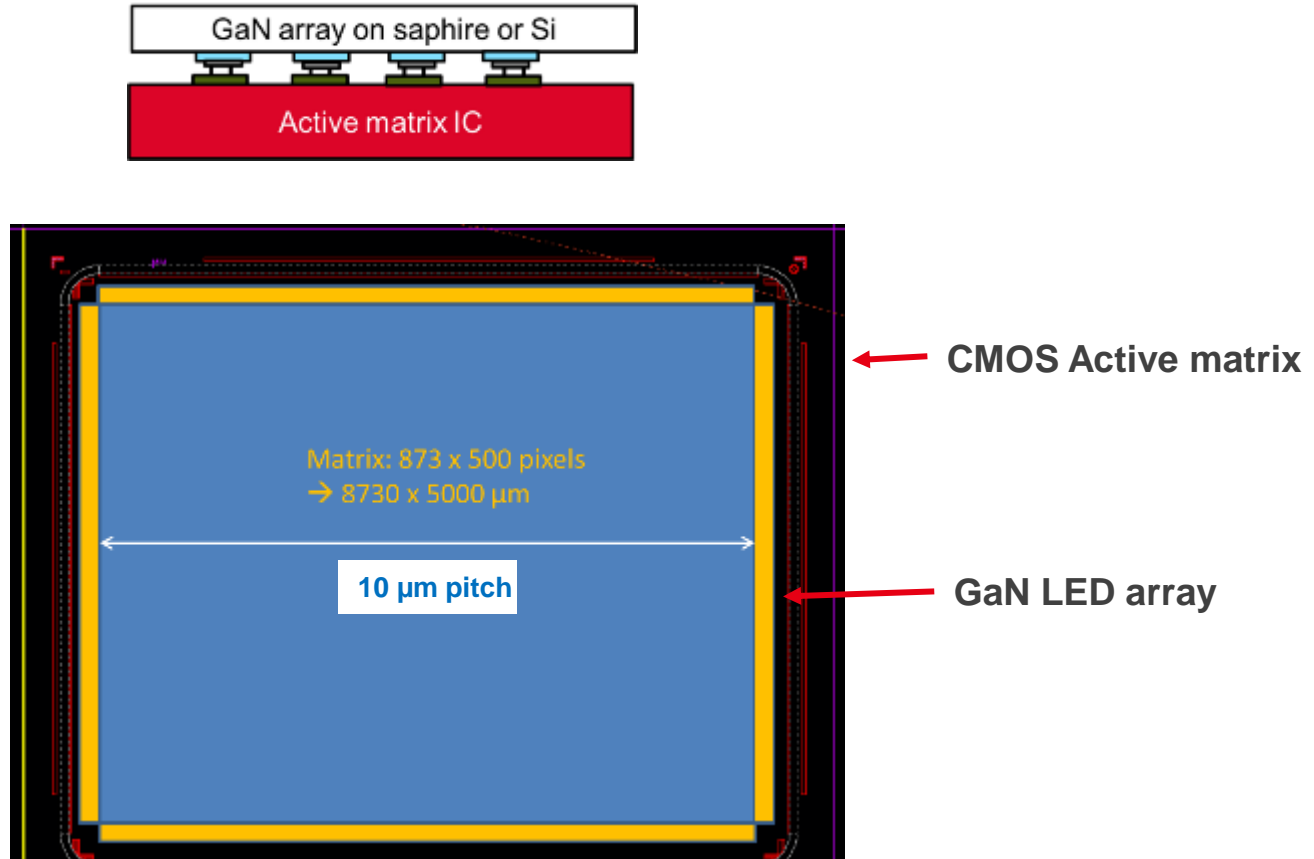
- Room temperature assembly using thermo-compression
- Few mN per connection
- Multi materials approach possible for insertion
- Standard IC technology

DEMONSTRATOR OF 10 μm PITCH GAN LED ARRAY MADE AT LETI

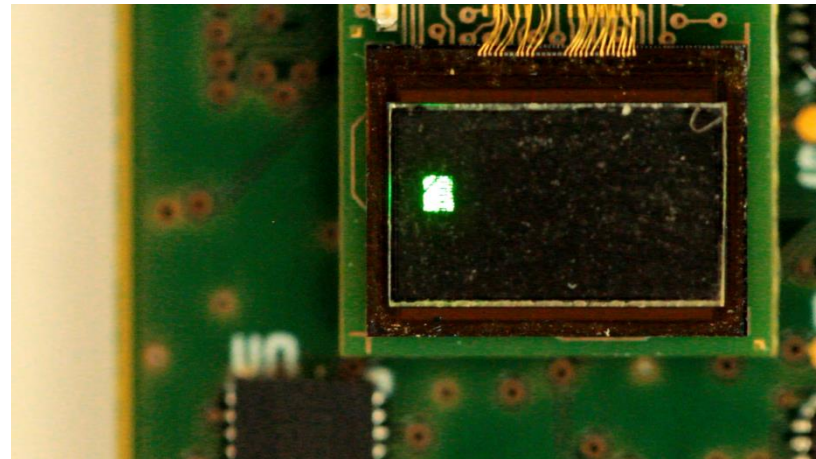
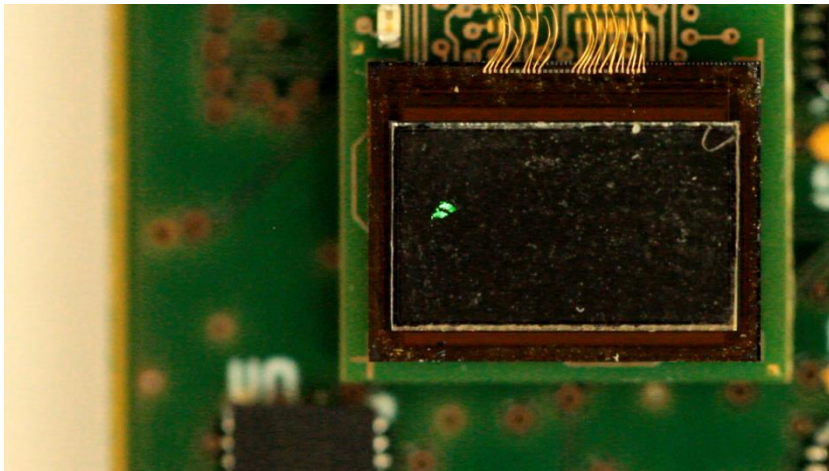


WVGA ACTIVE-MATRIX GAN LED MICRODISPLAY

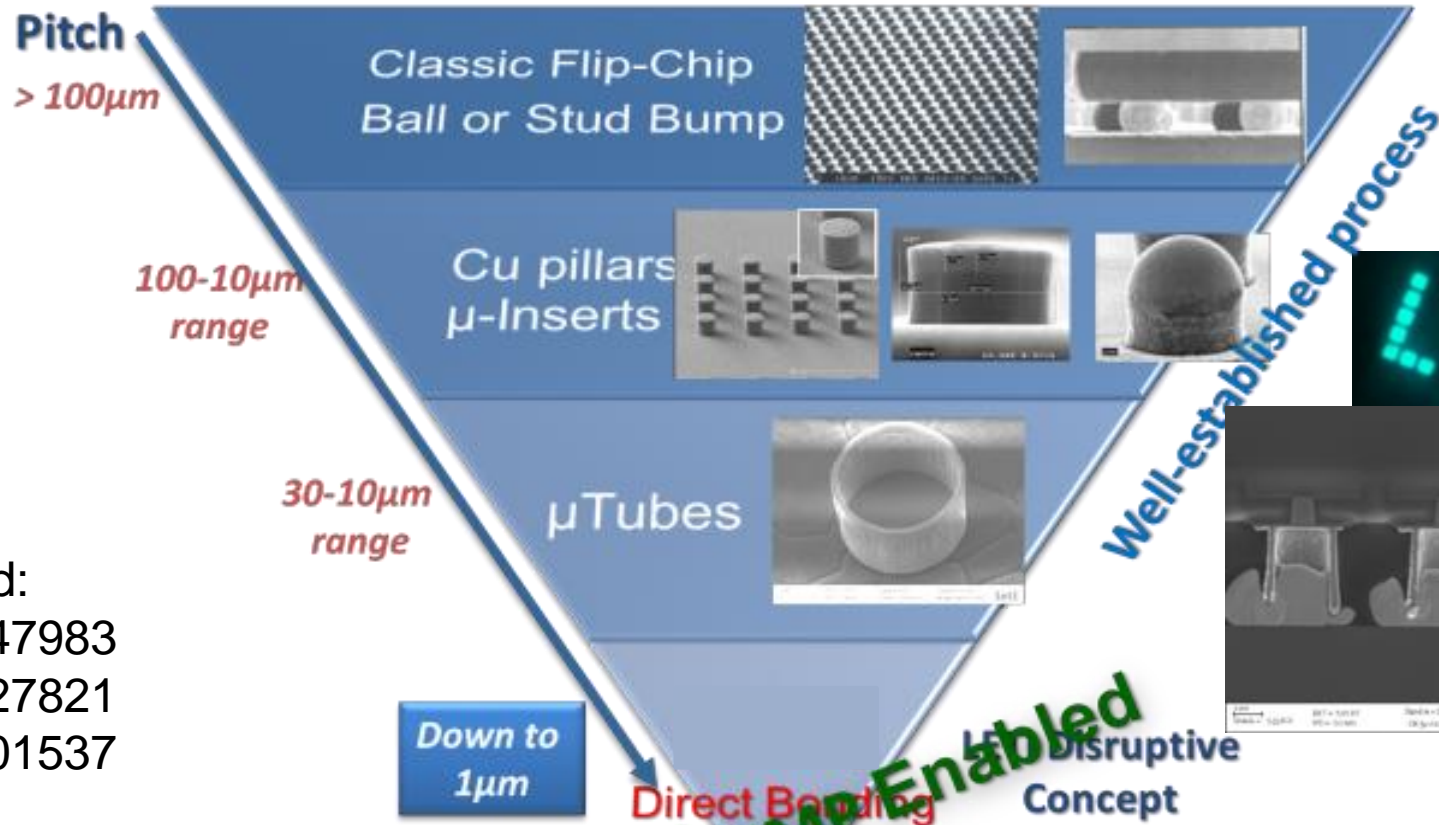
- Active-matrix WVGA (873 x 500) LED demonstrator



AMLED demo



LED MATRIX HYBRIDIZATION ON CMOS PORTFOLIO



Patent:
US8647983
US9027821
US8501537

ADVANTAGES

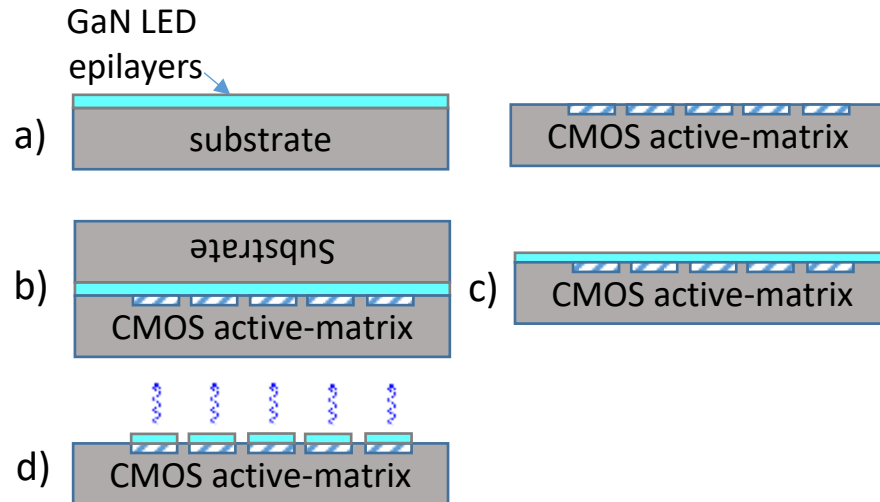
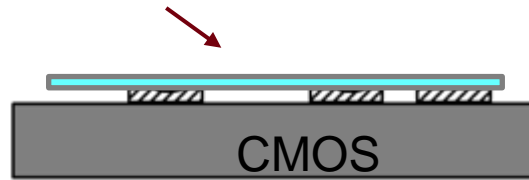
- ✓ Pitch $< 1\ \mu\text{m}$ achievable
- ✓ Done at RT, ambient pressure
- ✓ No glue needed

REQUIREMENTS

- Flatness @ all spatial level
- Surface Roughness of $\sim 0.5\ \text{nm RMS}$

Novel approach: transfer of GaN on CMOS

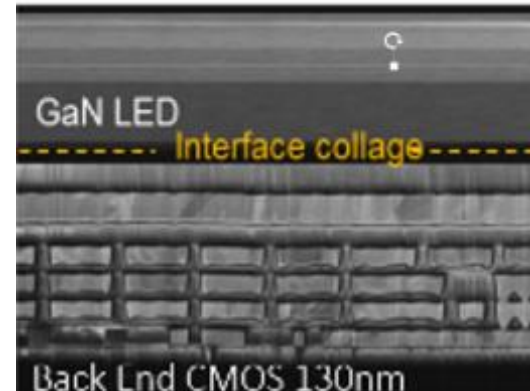
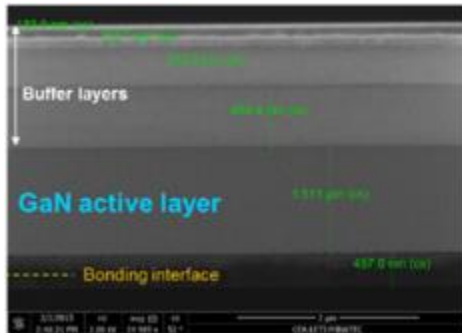
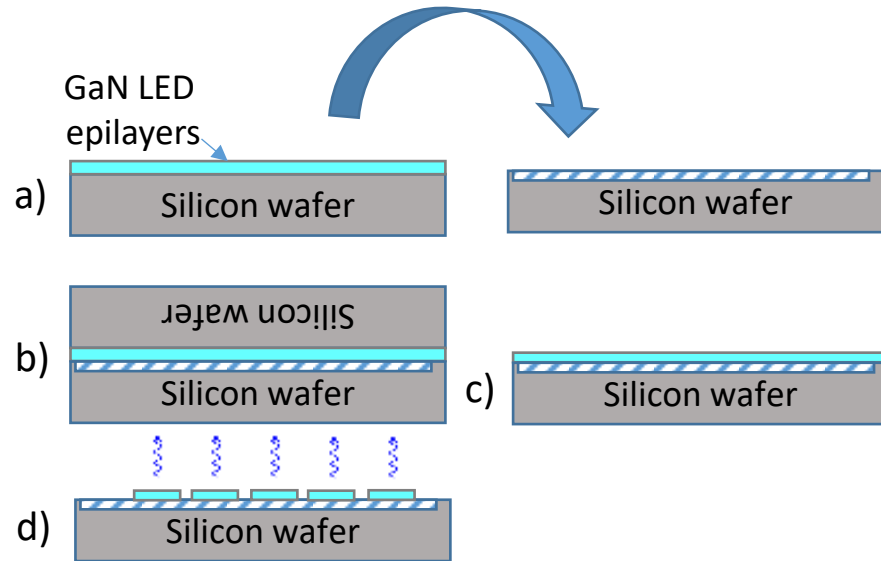
Monolithic, GaN transfer:



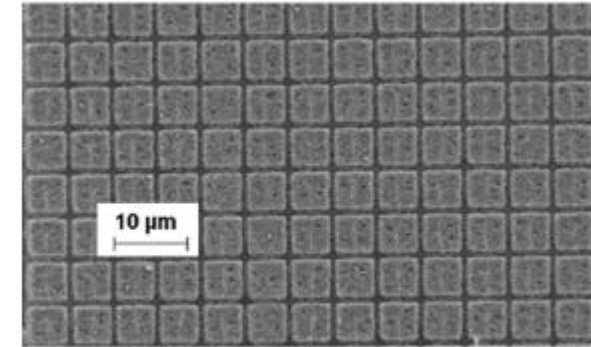
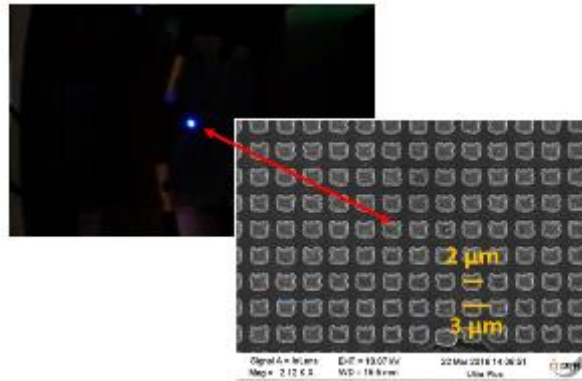
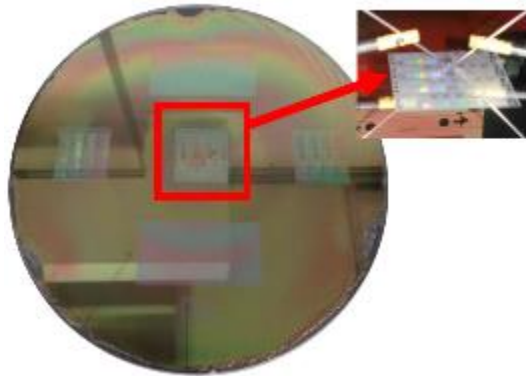
NOVEL APPROACH FOR GAN MICRODISPLAYS

Novel approach : transfer of GaN on CMOS

Proof-of-concept



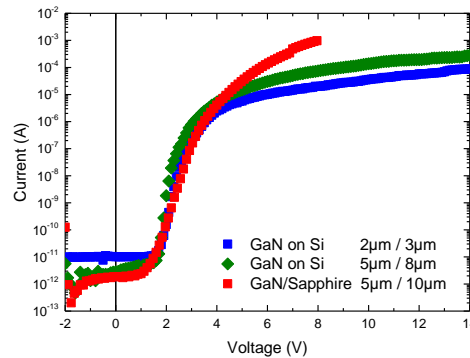
Proof-of-concept



Signal B = SE2

Mixage Signal = 0.0000

leti



Next steps:

- Epi LED Si; sapphire...
- LED processing
- Active matrix

Summary:

- Versatile: epi, metals, ..
- Small pixel pitch
- Full CMOS
- ...color

THE COLOR CHALLENGE

- 3 colors on same wafer
- small pitch (10 / 5 / 3 μm)
- crosstalk

Direct generation:

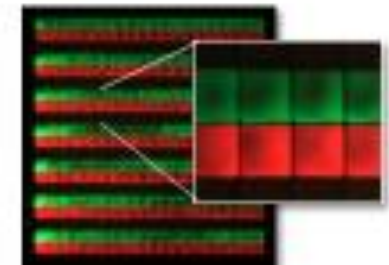
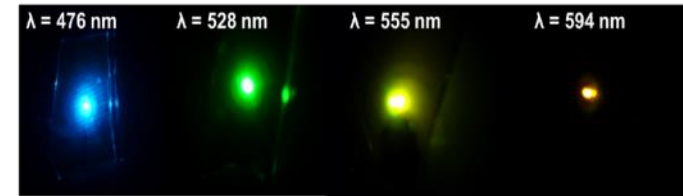
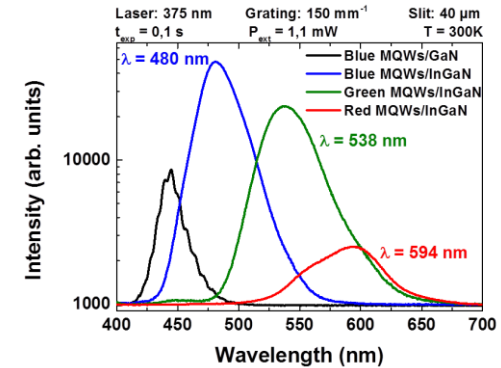
- Selective Area Growth (SAG)
- Epi stack (IOP, Ostendo)
-

→ Longterm

Color conversion:

Phosphors, QDs

2D layers

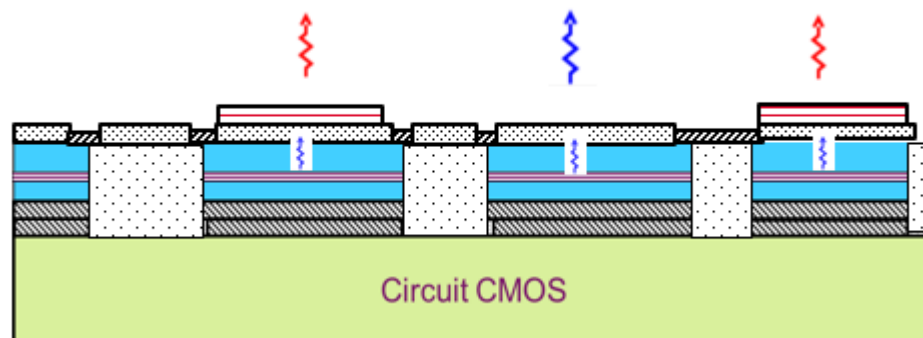
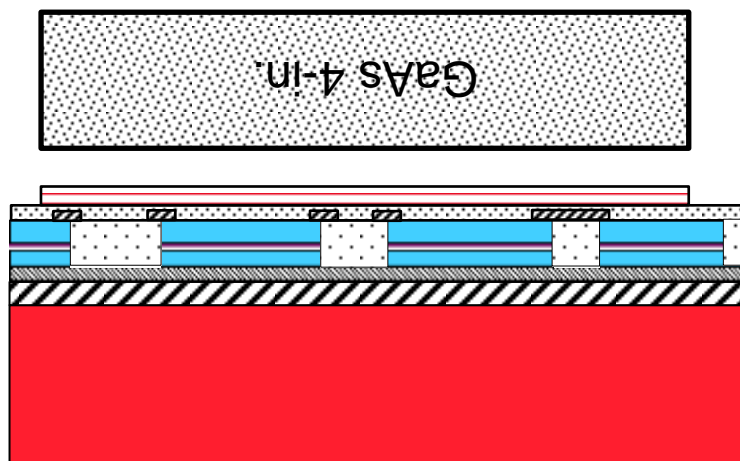


→ MQWs Green : InGaN/GaN/sapphire

→ MQWs Red : InGaAlP/InGaP/GaAs

SOLUTION FOR HIGH RESOLUTION FULL COLOR LED MICRODISPLAYS

→ Using color conversion with 2D materials, transferred on LED arrays



→ Solutions for full-color
Small pixel-pitch
Active matrix displays

THANK YOU

